



GC6603 CSP

1/2.66" 6Mega CMOS Image Sensor

Datasheet Preliminary

V0.1

2024-03-01

Ordering Information

◆ **GC6603-C62YA**

(Colored, 62PIN-CSP)

GENERATION REVISION HISTORY

Version.	Effective Date	Description of Changes	Prepared by
V0.1	2024-03-01	Beta version	DSC-AE Dept.

Galaxycore Incorporation

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Content

1. Sensor Overview	6
1.1 General Description	6
1.2 Features	7
2. Electrical Characteristics	9
2.1 Absolute Maximum Ratings	9
2.2 Operation Conditions	9
2.3 DC Characteristics	9
2.4 AC Characteristics	10
2.5 Power Consumption	10
3. CSP Package Specifications	11
3.1 Pin Descriptions	11
3.2 Package Specification	14
4. Optical Specifications	16
4.1 Readout Position	16
4.2 Pixel Array	17
4.3 Lens Chief Ray Angle (CRA)	18
4.4 QE Spectral Characteristics	19
5. Two-wire Serial Bus Communication	20
5.1 Protocol	20
5.2 Serial Bus Timing	21
6. MIPI Timing	23
6.1 Clock Lane Low-power	23
6.2 Data Burst	24
7. Function Description	25
7.1 Operation Mode	25
7.2 Power on Sequence	26
7.3 Power off Sequence	28
7.4 Black Level Calibration	29
7.5 Integration Time	29
7.6 Windowing	30
7.7 Frame Sync Mode	31
7.8 Binning Mode	32
7.9 Frame Structure	32
8. Register List	34

FIGURE CONTENT

Figure 1: Block Diagram	6
Figure 2: AC Characteristics.....	10
Figure 3: CSP Pin Top View.....	11
Figure 4: Mechanical Drawing View(μm)	14
Figure 5: Readout Position	16
Figure 6: Pixel Array	17
Figure 7 CRA Information.....	18
Figure 8 QE curve	19
Figure 9: Write operate (2 bytes address –1byte data format)	20
Figure 10: Read Operate (2 bytes address –1byte data format)	21
Figure 11: Serial Bus Timing	21
Figure 12: MIPI Clock Lane Time	23
Figure 13: MIPI Data Lane Time.....	24
Figure 14: Operation Mode.....	25
Figure 15: Power on Timing	26
Figure 16: Power off Timing	28
Figure 17: Windowing Mode	30
Figure 18: Frame Sync Configuration.....	31
Figure 21: Frame Structure	33

TABLE CONTENT

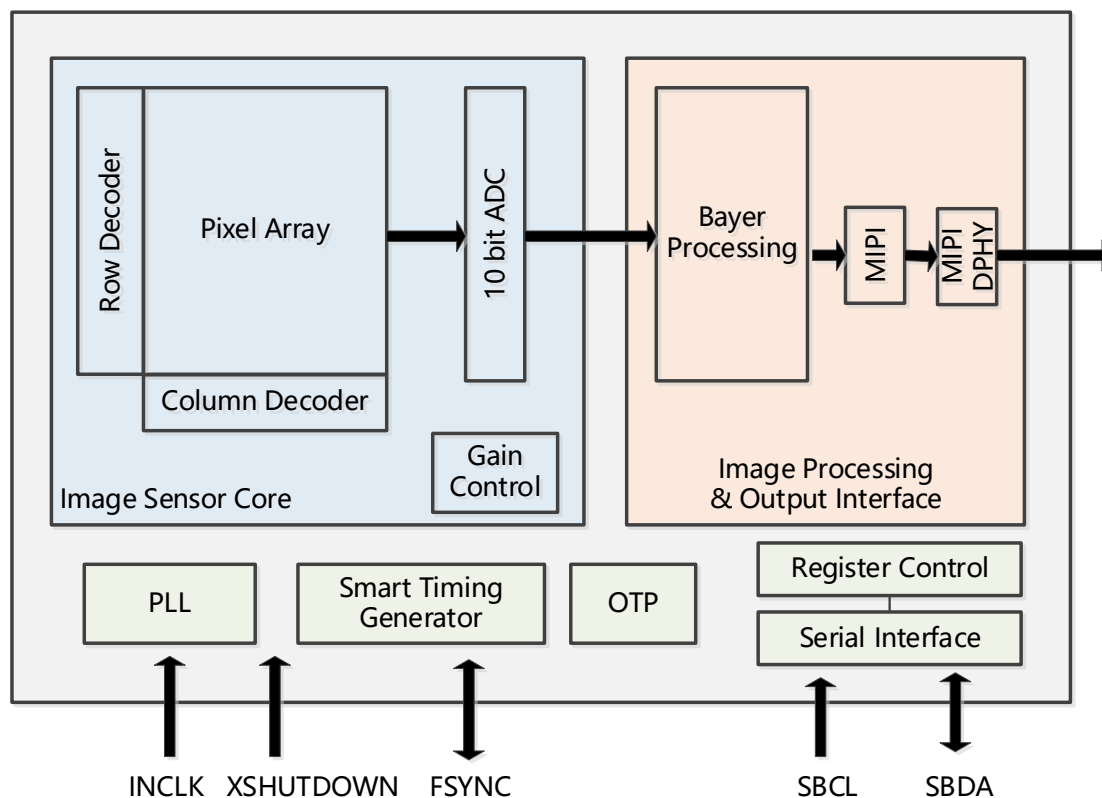
Table 1: Absolute Maximum Ratings	9
Table 2: Operation Conditions	9
Table 3: DC Characteristics	9
Table 4: AC Characteristics	10
Table 5: Power Consumption	10
Table 6: Pin Descriptions	11
Table 7: Package Specifications	15
Table 8: Mirror and Flip Information	16
Table 9: CRA Information	18
Table 10: Device ID	20
Table 11: Serial Bus Timing	21
Table 12: Operate State	25
Table 13: Power on Timing	26
Table 14: Power off Timing	28
Table 15: Shutter Time Register	29
Table 16: Window Set Register	30
Table 17: Out Window Set Register	31
Table 18: Binning mode Register	32
Table 19: Frame Length Register	32
Table 20: Line Length Register	33

1. Sensor Overview

1.1 General Description

GC6603 is a high quality 6Mega CMOS image sensor, for notebook camera digital camera and mobile phone camera applications. GC6603 incorporates a 2688H x 2048V active pixel array, on-chip 10-bit ADC, and image signal processor. It is programmable through a simple two-wire serial interface and has very low power consumption. It provides RAW10 and RAW8 data formats with MIPI interface.

Figure 1: Block Diagram



1.2 Features

◆ Optical size:	1/2.66 inch
◆ Pixel size:	2μm x 2μm BSI
◆ Active image size:	2688 x 2048
◆ Color Filter:	RGB Bayer
◆ Output formats:	Raw Bayer 10bit/8bit
◆ Interface:	MIPI
◆ Power supply requirement:	AVDD28: 2.7~2.9V (Typ. 2.8V) DVDD: 1.15~1.25V (Typ. 1.2V) IOVDD: 1.7~1.9V (Typ. 1.8V) AVDD18: 1.7~1.9V (Typ. 1.8V)
◆ Power Consumption:	130mW @Full Size @30fps
◆ Frame rate:	30fps@Full Size
◆ PLL support	
◆ Frame sync support (master/slave)	
◆ Windowing support	
◆ Mirror and Flip support	
◆ Binning Mode support (2x2)	
◆ OTP support	
◆ Analog Gain:	128X(Max)
◆ Sensitivity:	2.4 V/(Lux•s)
◆ Dynamic range:	80 dB
◆ MAX SNR:	38 dB
◆ Dark Current:	62 e-/s
◆ Micro lens chief ray angle (CRA):	18°(linear)
◆ Operation Temperature:	-30~85℃
◆ Stable Image temperature:	-20~60℃
◆ Storage temperature:	-40~125℃

◆ Package: CSP

2. Electrical Characteristics

2.1 Absolute Maximum Ratings

Table 1: Absolute Maximum Ratings

Description	Symbol	Rating	Unit	Note
Analogue absolute max	V _{AVDD_MAX}	-0.3~3.9	V	Refer to GND
Digital absolute voltages	V _{DVDD_MAX}	-0.3~1.8	V	
IO absolute max	V _{IOVDD_MAX}	-0.3~3.6	V	
AF absolute max	V _{AFVDD_MAX}	-0.3~3.6	V	
Digital input voltages	V _{IF_MAX}	-0.3~V _{IOVDD} +0.3	V	

Note: Digital input voltage: XCLK, SBCL, SBDA, XSHUTDOWN, FSYNC

2.2 Operation Conditions

Table 2: Operation Conditions

Description	Symbol	Min.	Typical	Max.	Unit
Analog power supply	V _{AVDD}	2.7	2.8	2.9	V
Digital power supply	V _{DVDD}	1.15	1.2	1.25	V
IO power supply	V _{IOVDD}	1.7	1.8	1.9	V
AF power supply	V _{AFVDD}	1.7	1.8	1.9	V
Digital input voltages	V _{IF}	0		IOVDD	V
Test temperature	T _{TEST}	21	25	27	°C

Note: 1. Digital input voltage: XCLK, SBCL, SBDA, XSHUTDOWN, FSYNC.

2. Test temperature: image quality test condition.

2.3 DC Characteristics

Table 3: DC Characteristics

Characteristics	Symbol	Min.	Typical	max	Unit
Input voltage HIGH	V _{IH}	0.7 x V _{IF}	-	-	V
Input voltage LOW	V _{IL}	-	-	0.3 x V _{IF}	V
Output voltage HIGH	V _{OH}	0.7 x V _{IOVDD}	-	-	V
Output voltage LOW	V _{OL}	-	-	0.3 x V _{IOVDD}	V

Note: Input voltage apply to XCLK, SBCL, SBDA, XSHUTDOWN, FSYNC.

2.4 AC Characteristics

Figure 2: AC Characteristics

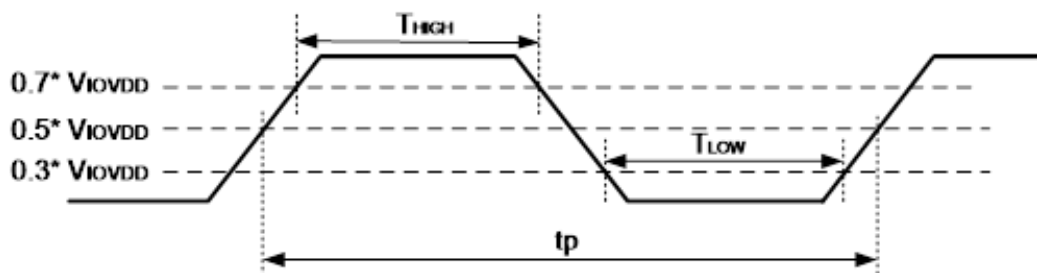


Table 4: AC Characteristics

Item	Symbol	Min.	Typ.	max	unit
Frequency	f_{SCK}	6	24	36	MHz
jitter (period, peak-to-peak)	T_{jitter}			600	ps
High level width	T_{HIGH}	0.4tp		0.6tp	ns
Low level width	T_{LOW}	0.4tp		0.6tp	ns
Duty Cycle	f_{DUTY}	40		60	%

2.5 Power Consumption

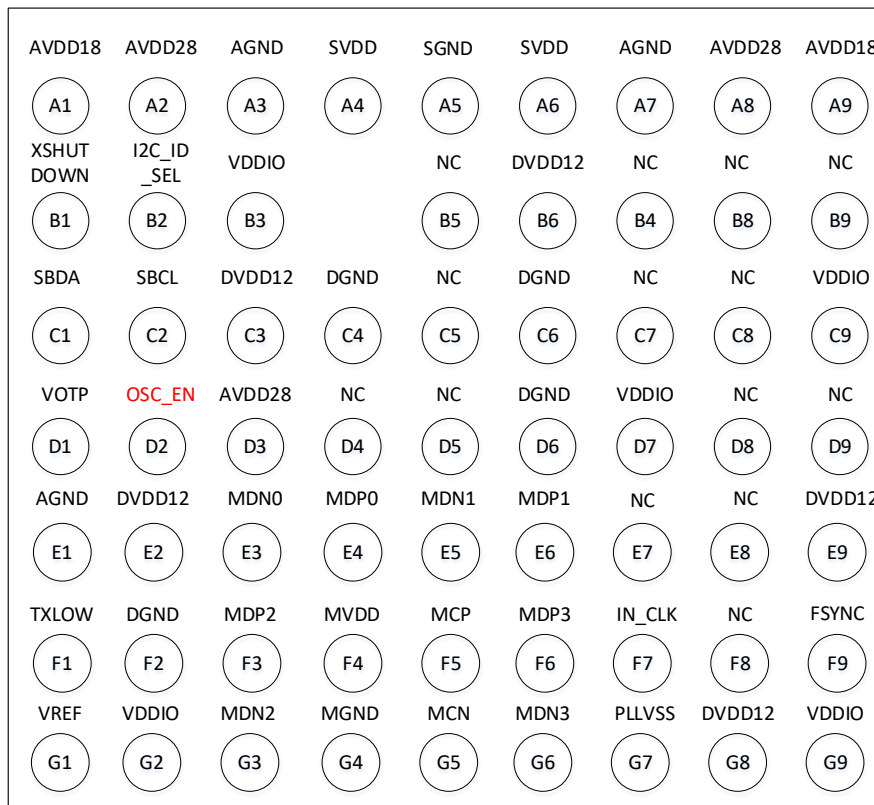
Table 5: Power Consumption

Item	Symbol	Min	Typ	Max	Unit
Full size @30fps MIPI 2lane	I_{AVDD}	-	9.2	-	mA
	I_{DVDD}	-	52.8	-	mA
	I_{IOVDD}	-	6.5	-	mA
	I_{AFVDD}	-	14.5	-	mA
Standby current	I_{AVDD}	-	0.5	-	μA
	I_{DVDD}	-	122	-	μA
	I_{IOVDD}	-	15.4	-	μA
	I_{AFVDD}	-	0.93	-	μA
Power off current	I_{total}	-	-	0	μA

- Note:**
1. All operate current are measured at 24MHz XCLK.
 2. Standby current is measured at XSHUTDOWN = L, XCLK=24MHz.
 3. We recommend that power should be turned off, when lower power consumption is required.

3. CSP Package Specifications

Figure 3: CSP Pin Top View



3.1 Pin Descriptions

Table 6: Pin Descriptions

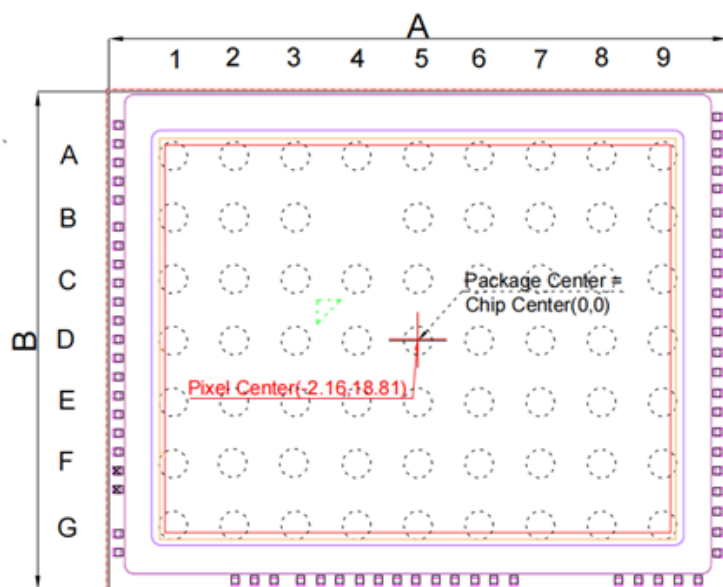
Pin	Name	Type	A/D	Description
A1	AVDD18	Power	A	Analog power supply:1.8V
A2	AVDD28	Power	A	Analog power supply:2.8V
A3	AGND	Ground	A	Ground for analog
A4	SVDD	Power	D	Digital power supply:1.2V
A5	SGND	Ground	D	Ground for digital
A6	SVDD	Power	D	Digital power supply:1.2V
A7	AGND	Ground	A	Ground for analog
A8	AVDD28	Power	A	Analog power supply:2.8V
A9	AVDD18	Power	A	Analog power supply:1.8V
B1	XSHUTDOWN	Input	D	Sensor power down control: (floating forbidden) 0: reset & standby; 1: normal work
B2	I2C_ID_SEL	Input	D	ID_SEL (floating forbidden) . 0:0x62, 1:0x20
B3	VDDIO	Power	D	I/O Power supply:1.8V
B4	/	/		/

Pin	Name	Type	A/D	Description
B5	NC	NC		NC
B6	DVDD12	Power	D	Digital power supply:1.2V
B7	NC	NC		NC
B8	NC	NC		NC
B9	NC	NC		NC
C1	SBDA	Input/Output	D	Two-wire serial bus, data.
C2	SBCL	Input	D	Two-wire serial bus, clock.
C3	DVDD12	Power	D	Digital power supply:1.2V
C4	DGND	Ground	D	Ground for digital
C5	NC	NC		NC
C6	DGND	Ground	D	Ground for digital
C7	NC	NC		NC
C8	NC	NC		NC
C9	VDDIO	Power	D	I/O Power supply:1.8V
D1	VOTP	Power	D	OTP power supply: 7V (floating available)
D2	OSC_EN	Input	D	Internal OSC supply (floating forbidden) Connected to GND when supplying MCLK external
D3	AVDD28	Power	A	Analog power supply:2.8V
D4	NC	NC		NC
D5	NC	NC		NC
D6	DGND	Ground	D	Ground for digital
D7	VDDIO	Power	D	I/O Power supply:1.8V
D8	NC	NC		NC
D9	NC	NC		NC
E1	AGND	Ground	A	Ground for analog
E2	DVDD12	Power	D	Digital power supply:1.2V
E3	MDN0	Output	D	MIPI data <0> (-).
E4	MDP0	Output	D	MIPI data <0> (+).
E5	MDN1	Output	D	MIPI data <1> (-).
E6	MDP1	Output	D	MIPI data <1> (+).
E7	NC	NC		NC
E8	NC	NC		NC
E9	DVDD12	Power	D	Digital power supply:1.2V
F1	TXLOW	Power	A	Internal power supply.
F2	DGND	Ground	D	Ground for digital
F3	MDP2	Output	D	MIPI data <2> (+)
F4	MVDD	Power	D	Digital power supply:1.2V

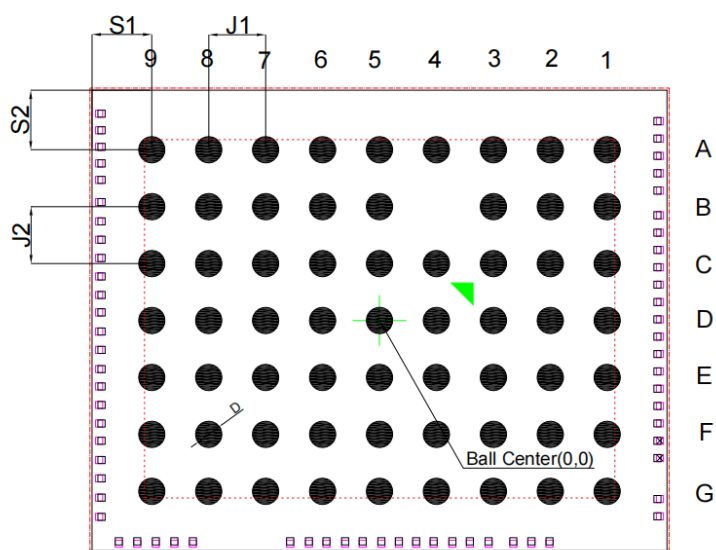
Pin	Name	Type	A/D	Description
F5	MCP	Output	D	MIPI clock (+)
F6	MDP3	Output	D	MIPI data <3> (+)
F7	IN_CLK	Input	D	Sensor input clock
F8	NC	NC		NC
F9	FSYNC	Input	D	Frame sync control
G1	VREF	Power	A	Internal power supply.
G2	VDDIO	Power	D	I/O power supply:1.8V
G3	MDN2	Output	D	MIPI data <2> (-)
G4	MGND	Ground	D	Ground for digital
G5	MCN	Output	D	MIPI clock (-)
G6	MDN3	Output	D	MIPI data <3> (-)
G7	PLLVS	Ground	D	Ground for PLL
G8	DVDD12	Power	D	Digital power supply:1.2V
G9	VDDIO	Power	D	I/O power supply:1.8V

3.2 Package Specification

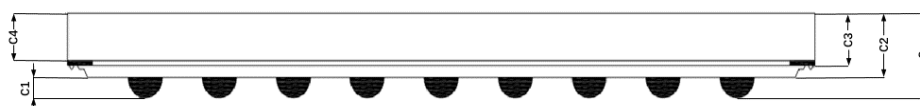
Figure 4: Mechanical Drawing View(μm)



Top View(Bumps Down)



Back View(Bumps Up)



Side View

Table 7: Package Specifications

Description	symbol	Nominal	Min	Max
		Millimeters		
Package Body Dimension X	A	6.564	6.539	6.589
Package Body Dimension Y	B	5.259	5.234	5.284
Package Height	C	0.676	0.621	0.731
Ball Height	C1	0.150	0.120	0.180
Package Body Thickness	C2	0.526	0.491	0.561
Thickness from top glass surface to wafer	C3	0.345	0.330	0.360
Glass Thickness	C4	0.300	0.290	0.310
Ball Diameter	D	0.300	0.270	0.330
Total Ball Count	N	62(15NC)		
Ball Count X axis	N1	9		
Ball Count Y axis	N2	7		
Pins pitch X axis	J1	0.650	0.640	0.660
Pins pitch Y axis	J2	0.650	0.640	0.660
BGA ball center to package center offset in X-direction	X	0.000	-0.025	0.025
BGA ball center to package center offset in Y-direction	Y	0.000	-0.025	0.025
BGA ball center to chip center offset in X-direction	X1	0.000	-0.025	0.025
BGA ball center to chip center offset in Y-direction	Y1	0.000	-0.025	0.025
Edge to Pin Center Distance along X1	S1	0.682	0.652	0.712
Edge to Pin Center Distance along Y1	S2	0.6795	0.6495	0.7095

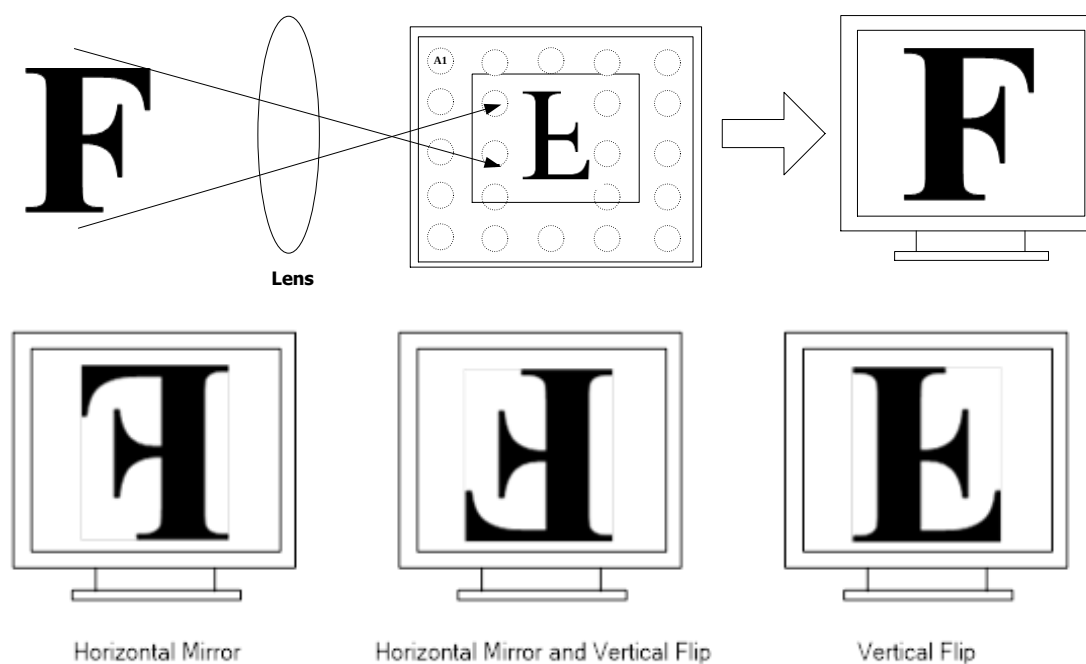
Note: The package center, optical center, and BGA center of the chip are not coincident. If setting the package center as the origin (0, 0), the BGA center coordinate is (0, 0), the optical center coordinate is (-2.16, 18.81), with μm unit

4. Optical Specifications

4.1 Readout Position

GC6603 default status is readout from the lower left corner with pin A1 located in the upper left corner. The image is inverted vertically and horizontally by the lens, so proper image output results when Pin A1 is located in the upper left corner.

Figure 5: Readout Position



Readout direction can be set by the registers.

Table 8: Mirror and Flip Information

Function	Register Address	Register Value	First Pixel
Normal	0x0063/0x022c/0x0722	0/0/0	R
Horizontal mirror	0x0063/0x022c/0x0722	1/1/2	Gr
Vertical Flip	0x0063/0x022c/0x0722	2/2/0	Gb
Horizontal Mirror and Vertical Flip	0x0063/0x022c/0x0722	3/3/2	B

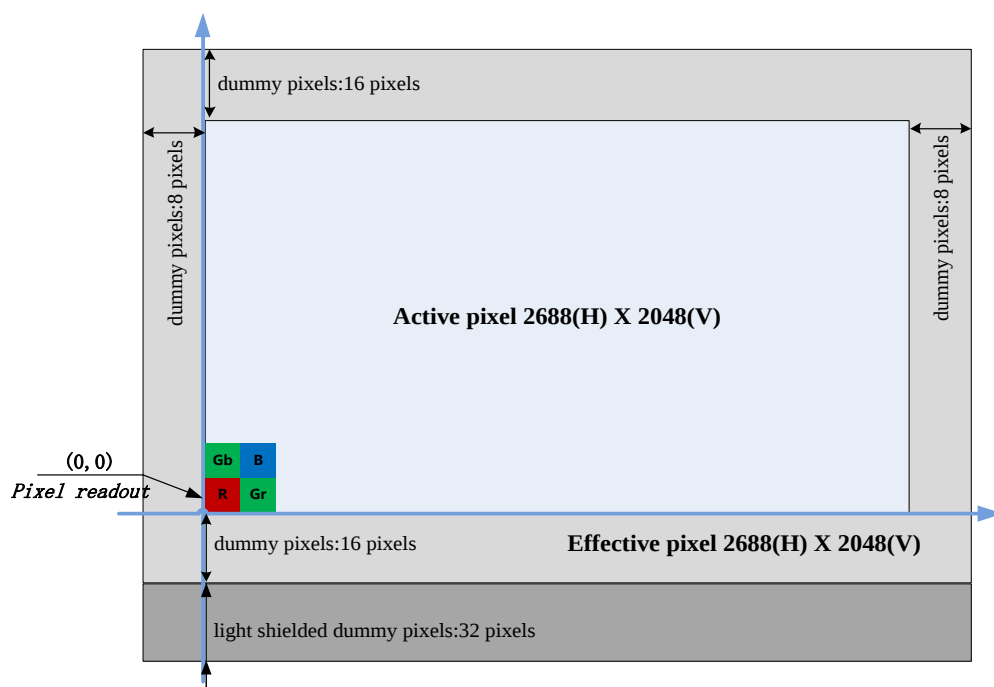
4.2 Pixel Array

Pixel array is covered by Bayer pattern color filters. The primary color GR/BG array is arranged in line-alternating way.

If no flip in column, column is read out from 0 to 2687. If flip in column, column is read out from 2687 to 0.

If no flip in row, row is read out from 0 to 2048. If flip in row, row is read out from 2047 to 0.

Figure 6: Pixel Array



4.3 Lens Chief Ray Angle (CRA)

Figure 7 CRA Information

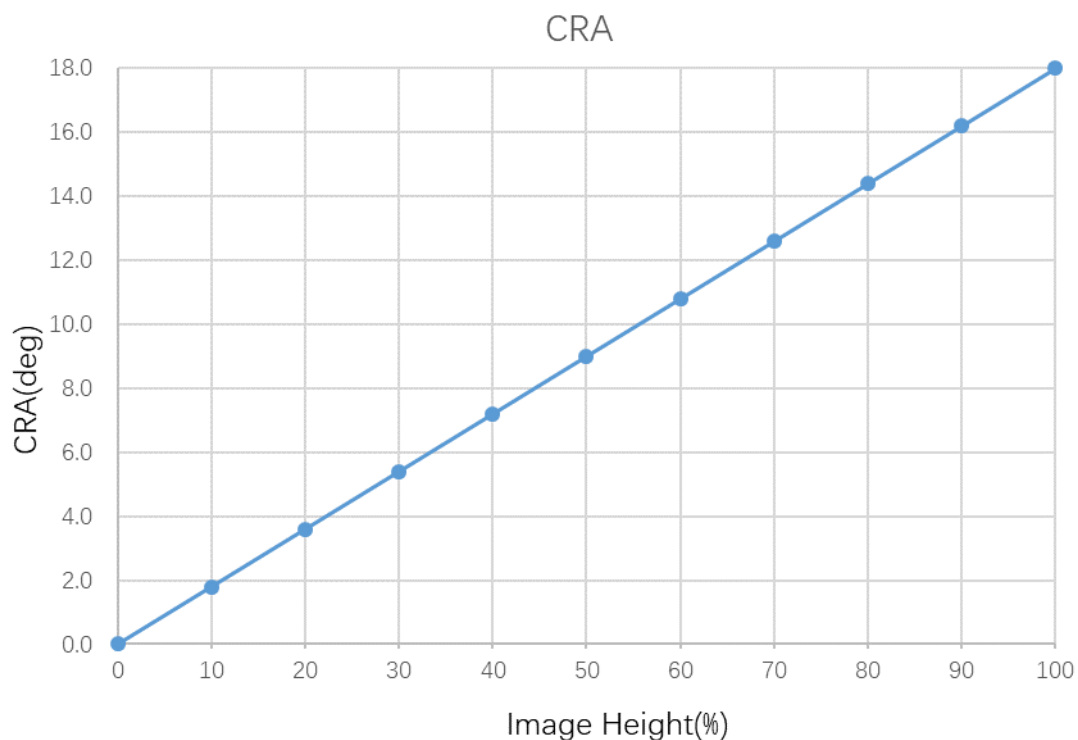


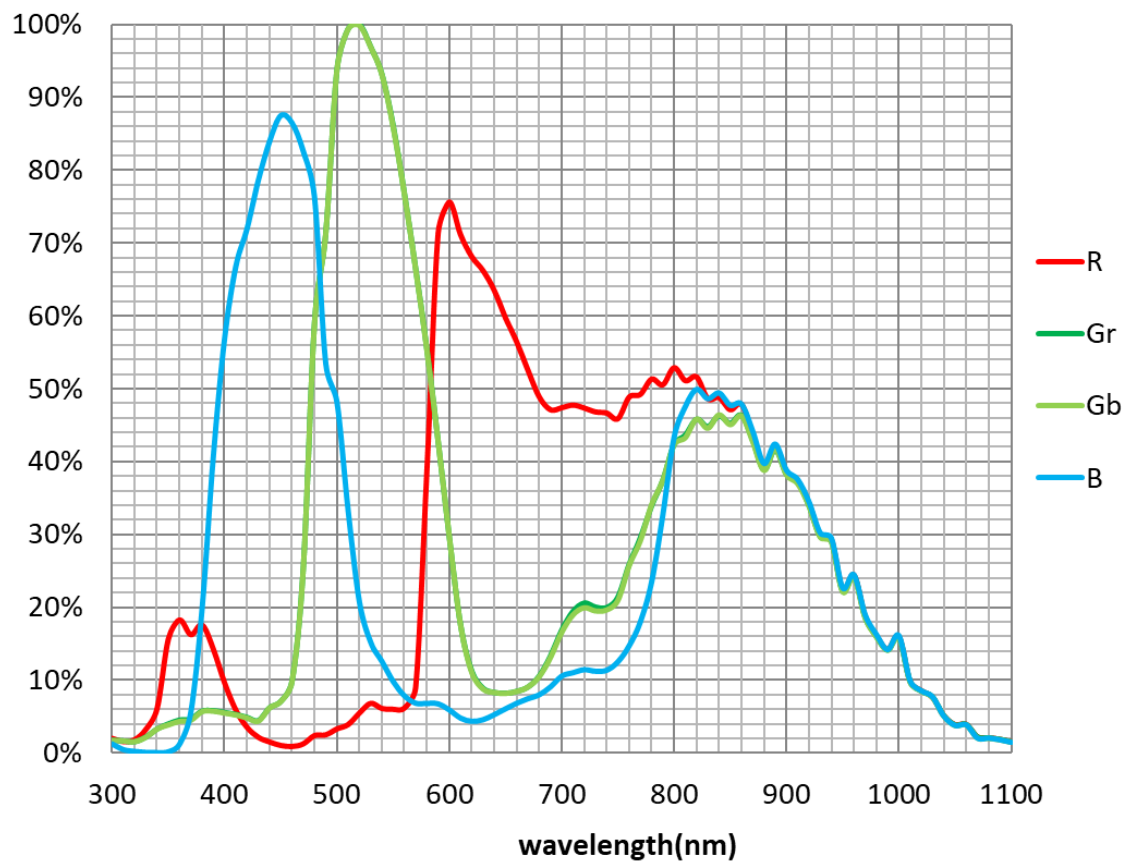
Table 9: CRA Information

Image Heigh (%)	Image Height (mm)	CRA (degree)
0	0.000	0
10	0.332	1.8
20	0.663	3.6
30	0.995	5.4
40	1.327	7.2
50	1.659	9.0
60	1.990	10.8
70	2.322	12.6
80	2.654	14.4
90	2.986	16.2
100	3.317	18.0

4.4 QE Spectral Characteristics

The optical spectrum of QE is below:

Figure 8 QE curve



5. Two-wire Serial Bus Communication

GC6603 Device Address:

Table 10: Device ID

ID_SEL	Slave address write mode	Slave address read mode
0(default)	0x62	0x63
1	0x20	0x21

NOTE: When IDSEL0/IDSEL1 is “High”, it means connect to IOVDD. When IDSEL0/IDSEL1 is “Low”, you should connect it to DGND.

5.1 Protocol

The host must perform the role of a communications master and GC6603 acts as either a slave receiver or transmitter. The master must do:

- ◆ Generate the **Start(S)/Stop(P)** condition
- ◆ Provide the serial clock on **SBCL**

Figure 9: Write operate (2 bytes address –1byte data format)

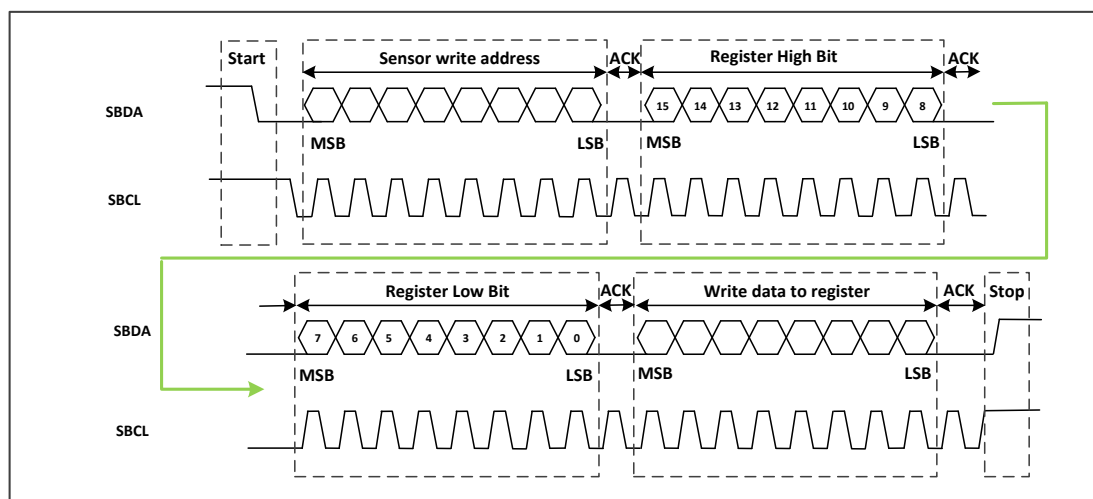
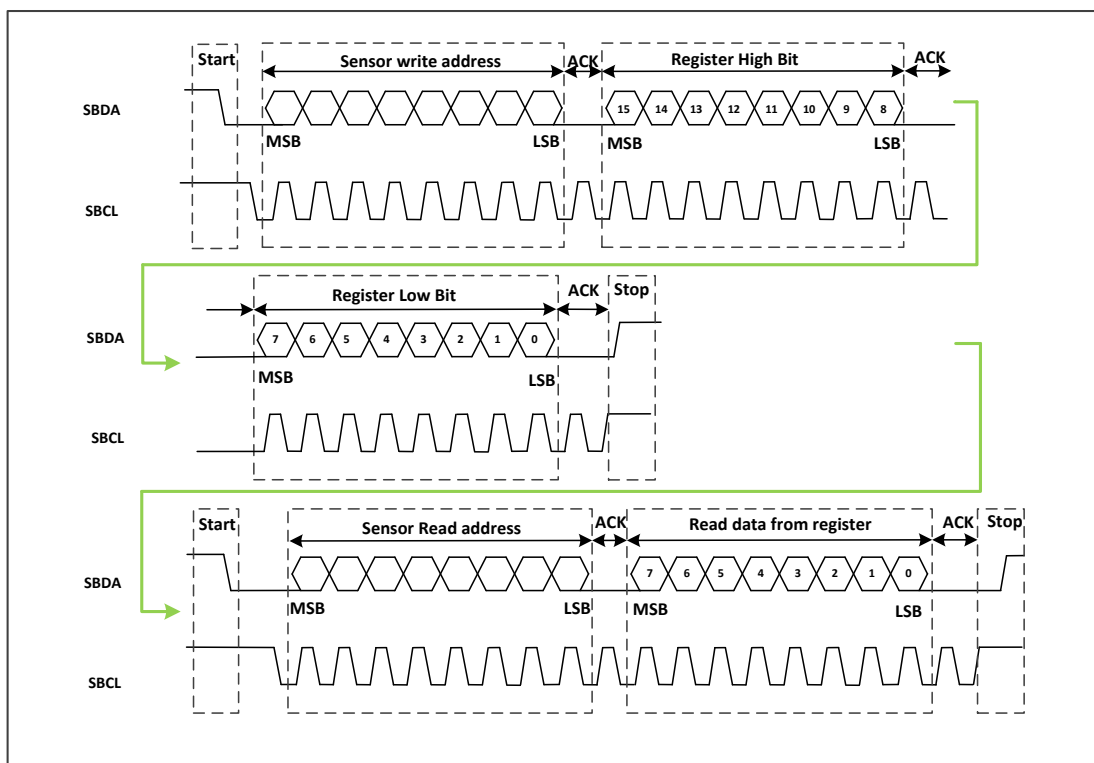


Figure 10: Read Operate (2 bytes address –1byte data format)



5.2 Serial Bus Timing

Figure 11: Serial Bus Timing

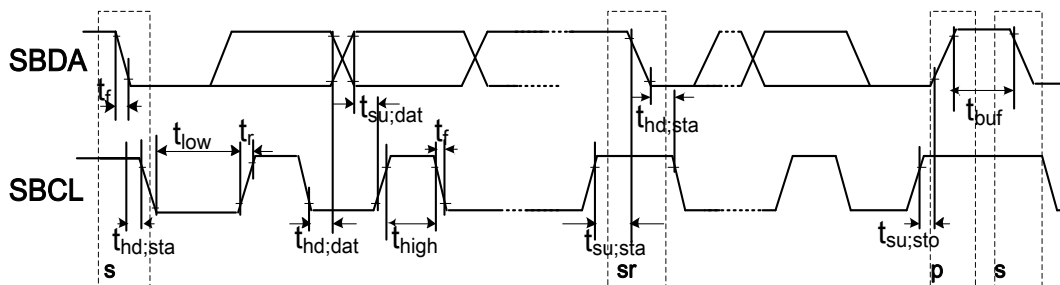


Table 11: Serial Bus Timing

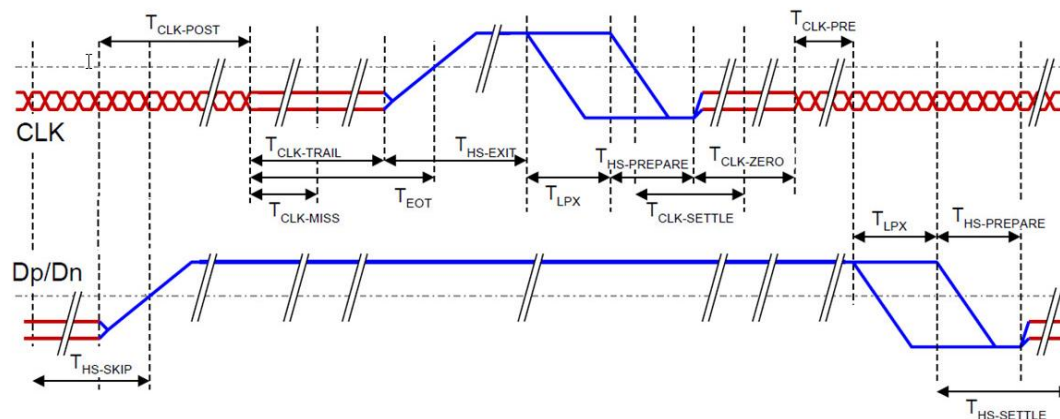
Parameter	Symbol	Min	Typ.	Max	Unit
SBCL clock frequency	F_{scl}	0	--	400	KHz
Bus free time between a stop and a start	t_{buf}	1.3	--	--	μs
Hold time for a repeated start	$t_{hd;sta}$	0.6	--	--	μs
LOW period of SBCL	t_{low}	1.3	--	--	μs
HIGH period of SBCL	t_{high}	0.6	--	--	μs
Set-up time for a repeated start	$t_{su;sta}$	600	--	--	ns
Data hold time	$t_{hd;dat}$	0	--	900	ns

Data Set-up time	$t_{su,dat}$	100	--	--	ns
Rise time of SBCL, SBDA	t_r	--	--	300	ns
Fall time of SBCL, SBDA	t_f	--	--	300	ns
Set-up time for a stop	$t_{su,sto}$	0.6	--	--	μs
Capacitive load of bus line (SBCL, SBDA)	C_b	--	--	100	pf

6. MIPI Timing

6.1 Clock Lane Low-power

Figure 12: MIPI Clock Lane Time

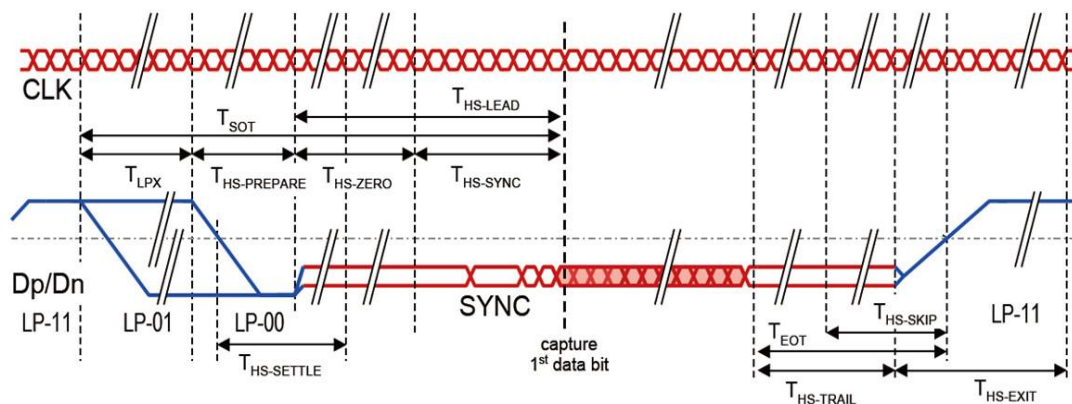


Notice:

- ◆ Clock must be reliable during high speed transmission and mode-switching.
 - ◆ Clock can go to LP only if data lanes are in LP (and nothing relies on it).
 - ◆ In Low-Power data lanes are conceptually asynchronous (independent of the high speed clock).
- $T_{CLK_HS_PREPARE}$: setting by Register 0x0122
 - T_{CLK_ZERO} : setting by Register 0x0123
 - T_{CLK_PRE} : setting by Register 0x0124
 - T_{CLK_POST} : setting by Register 0x0125
 - T_{CLK_TRAIL} : setting by Register 0x0126

6.2 Data Burst

Figure 13: MIPI Data Lane Time



Notice:

- ◆ Clock keeps running and samples data lanes (except for lanes in LPS).
- ◆ Unambiguous leader and trailer sequences required to distill real bits.
- ◆ Trailer is removed inside PHY (a few bytes).
- ◆ Time-out to ignore line values during line state transition.
 - T_{LPX} : setting by Register 0x0121
 - $T_{HS_PREPARE}$: setting by Register 0x0129
 - T_{HS_ZERO} : setting by Register 0x012a
 - T_{HS_TRAIL} : setting by Register 0x012b
 - T_{HS_EXIT} : setting by Register 0x0127

7. Function Description

7.1 Operation Mode

Figure 14: Operation Mode

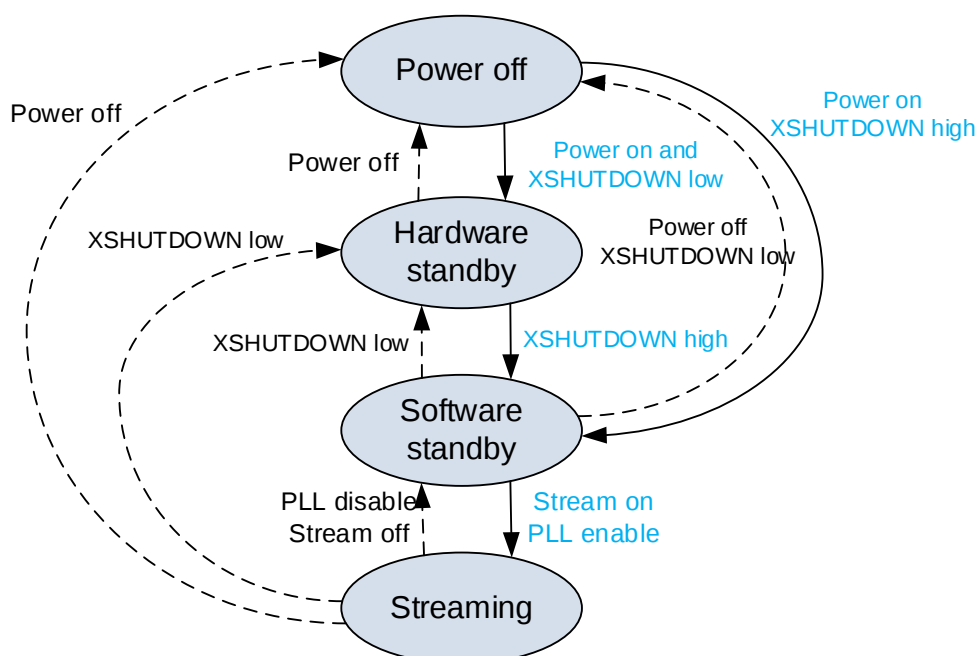


Table 12: Operate State

Power state	Description	Activate
Power off	Power supplies are turned off	None
Hardware standby	No communication with sensor, low level on XSHUTDOWN	XSHUTDOWN low
Software standby	Two- wire serial communication with sensor is possible, pll is ready for fast return to streaming mode	Stream mode off PLL disable XSHUTDOWN high
Streaming	Sensor is fully powered and streaming image data on the MIPI CSI-2 bus	All Pad Enabled

7.2 Power on Sequence

Figure 15: Power on Timing

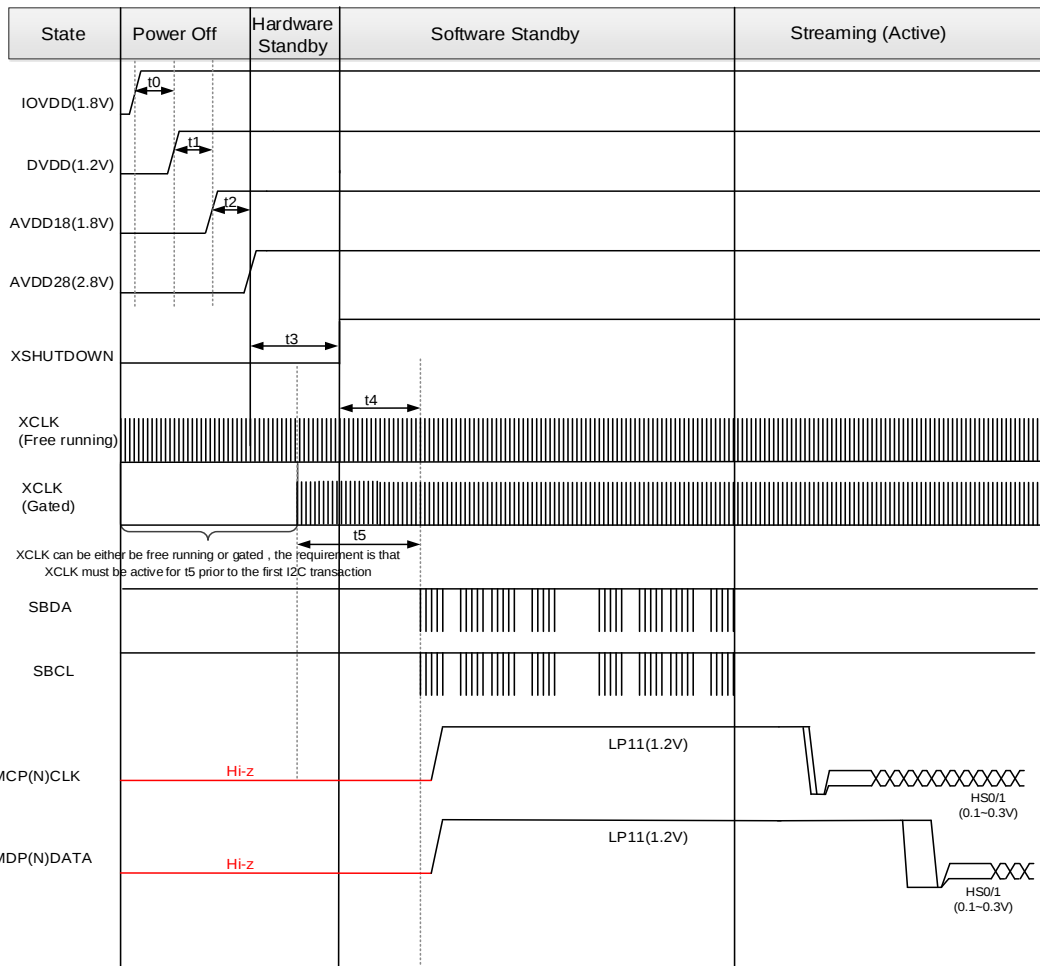


Table 13: Power on Timing

Parameter	Description	Min.	Max.	Unit
t0	From IOVDD power on to DVDD power on	0	-	μs
t1	From DVDD power on to AVDD18 power on	0	-	μs
t2	From AVDD18 power on to AVDD28 power on	0	-	μs
t3	From power on to XSHUTDOWN pull high	0	-	μs
t4	XSHUTDOWN rising to first I2C transaction	50	-	μs
t5	Minimum No. of XCLK cycles prior to the first I2C transaction	1200	-	XCLK

Note: 1. The suggested sequence is IOVDD powered on first, then DVDD12, AVDD18, and AVDD28 last.

2. Register should be reloaded before works.

7.3 Power off Sequence

Figure 16: Power off Timing

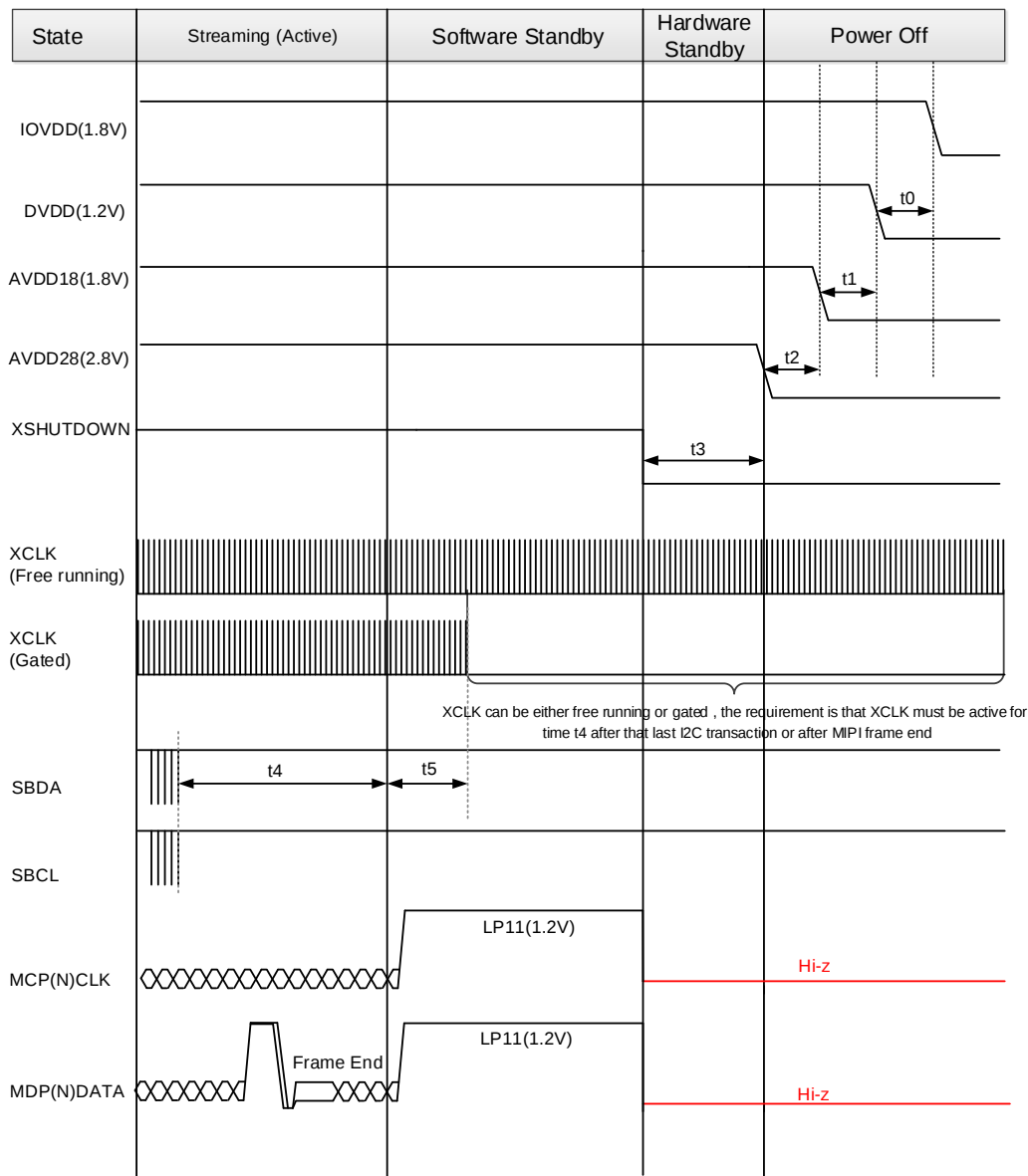


Table 14: Power off Timing

Parameter	Description	Min.	Max.	Unit
t_0	From DVDD power off to IOVDD power off	0	-	μs
t_1	From AVDD18 power off to DVDD power off	0	-	μs
t_2	From AVDD28 power off to AVDD18 power off	0	-	μs
t_3	From XSHUTDOWN pull down to power off	0	-	μs
t_4	Enter Software Standby command – Device in Software Standby mode	0	-	μs

t5	Minimum number of XCLK cycles after the last transaction or MIPI frame end code.	2000		XCLK
----	--	------	--	------

- Note:
1. IOVDD/DVDD12/AVDD18/AVDD28 may fall in any order. The suggested sequence is AVDD28 first, then AVDD18, DVDD, and IOVDD powered off last.
 2. If the sensor's power cannot be cut off, please keep power supply, then set XSHUTDOWN pin low. It will make sensor standby.
 3. If the standby sequence needs to be modified, please contact FAE of *Galaxycore Inc.*

7.4 Black Level Calibration

Black level is caused by pixel characteristics and analog channel offset, which makes poor image quality in dark condition and color balance, to reduce these, sensor automatically calibrates the black level every frame with light shield pixel array.

7.5 Integration Time

The integration time is controlled by the shutter time registers. When you want to set an exposure value that is bigger than the current frame length value, you should first set a new frame length and make sure that it's bigger than the exposure value you'd like to set.

Table 15: Shutter Time Register

Addr.	Register name	Description
0x0202	Shutter time	[5:0] shutter time[13:8]
0x0203		[7:0] shutter time[7:0]

7.6 Windowing

GC6603 has a rectangular pixel array 2688 x 2048, it can be windowed by output size control, the output image windowing can be used to adjust output size, and it will affect field angle.

Figure 17: Windowing Mode

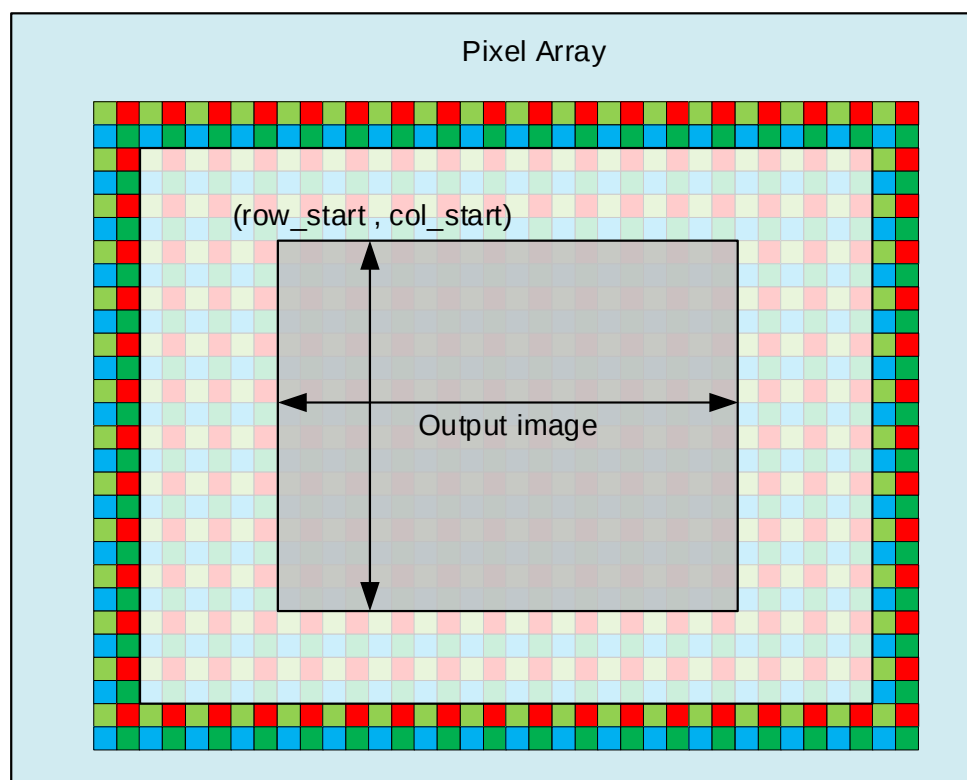


Table 16: Window Set Register

Addr.	Register name	Description
0x034a	win_height	[3:0] win_height[11:8]
0x034b		[7:0] win_height[7:0]
0x0348	win_width	[3:0] win_width[11:8]
0x0349		[7:0] win_width[7:0]
0x0346	Row start	[3:0] row_start[11:8]
0x0347		[7:0] row_start [7:0]
0x070d	Col start	[2:0] col_start[10:8]
0x070c		[7:0] col_start[7:0]

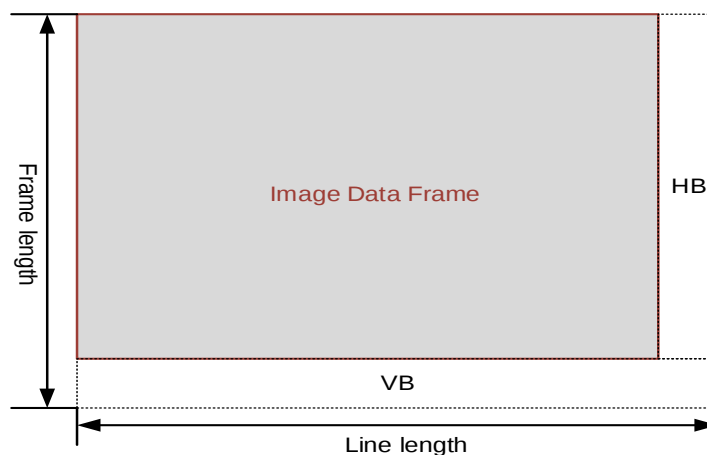
Table 17: Out Window Set Register

Addr.	Register name	Description
0x009a	out_win_x1	[3:0] out_win_x1[11:8]
0x009b		[7:0] out_win_x1[7:0]
0x0098	out_win_y1	[3:0] out_win_y1[11:8]
0x0099		[7:0] out_win_y1[7:0]
0x0094	out_win_width	[3:0] out_win_width[11:8]
0x0095		[7:0] out_win_width[7:0]
0x0096	out_win_height	[3:0] out_win_height[11:8]
0x0097		[7:0] out_win_height[7:0]

7.7 Frame Sync Mode

GC6603 can support hardware frame sync for dual camera application. It can be set both master and slave sensor. When use this mode, the two sensor's FSYNC pin must connect to each other.

Figure 18: Frame Sync Configuration



Master Mode:

When GC6603 operates as a master device, it controls vertical synchronous timings and outputs synchronous signal called Vsync signal or Fsync signal from the FSYNC pin.

Slave Mode:

GC6603 can be worked as a slave and automatically synchronized within

a certain VSYNC time period. It is important to control two image sensors' rolling shutters with the same timing.

7.8 Binning Mode

GC6603 has Binning mode which support a lower resolution output with high frame rate. The row or col can be independent controlled. However, only the row binning can increase frame rate.

Table 18: Binning mode Register

Addr.	Register name	Description
0x0223	binning_mode	[4] col bin2 [0] row bin2

7.9 Frame Structure

Frame structure is controlled by line length, frame length, window height, window width.

Frame length control:

Frame length is controlled by window height, minimum VB and shutter time.

◆ Frame length depend shutter time.

- Minimum frame length = window height + 52 +VB (VB_min = 0)
- If shutter time < minimum frame length: Actual frame length = minimum frame length
- If shutter time > minimum frame length: Actual frame length = shutter time + 8 (recommended).

Table 19: Frame Length Register

Addr.	Register name	Description
0x0340	Frame length	[5:0] frame length[13:8]
0x0341		[7:0] frame length[7:0]

0x029d	Minimum VB	[7:0] min_vb[7:0]
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Line length control:

Line length control for internal set, and not recommended to be modified.

Table 20: Line Length Register

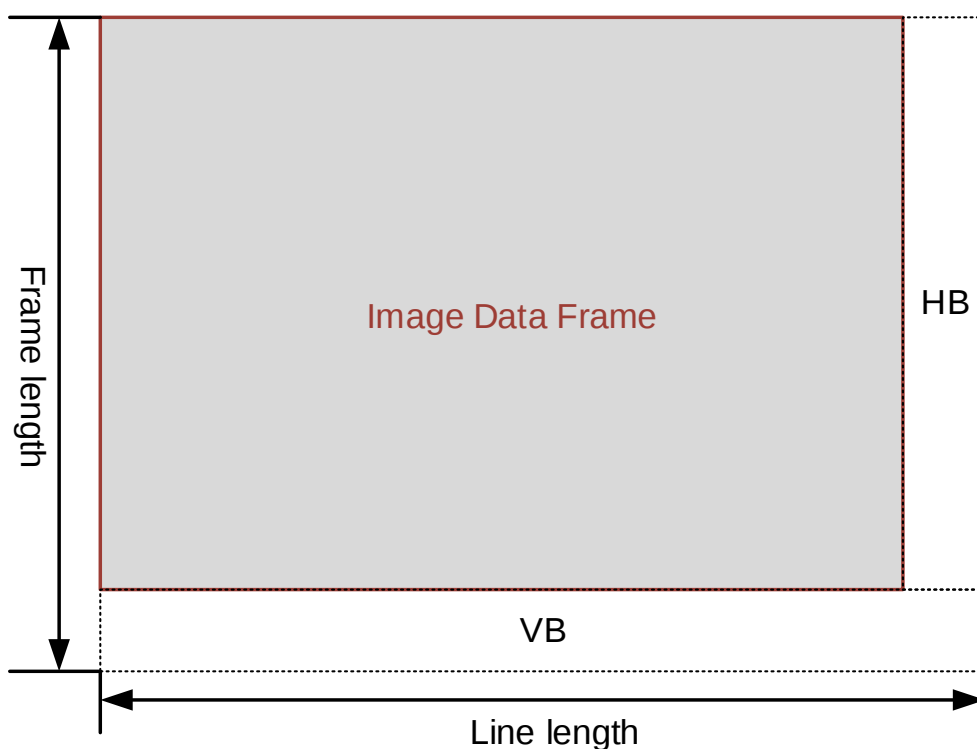
Addr.	Register name	Description
0x0342	Line length	[7:0] Line length[15:8]
0x0343		[7:0] Line length[7:0]

Blank time control:

Line blank time is controlled by line length.

Frame blank time = frame length – out window height

Figure 19: Frame Structure



8. Register List

System Register:

Address	Name	Default	R/W	Description
0x03f2	Sensor_ID_HIGH	0x56	RO	Sensor_ID
0x03f3	Sensor_ID_LOW	0x23	RO	Sensor_ID

Analog & CISCTL:

Address	Name	Default	R/W	Description
0x0202	Exposure[13:8]	0x00	RW	[5:0] Exposure[13:8]
0x0203	Exposure[7:0]	0x10	RW	[7:0] Exposure[7:0]
0x0342	CISCTL_hb[15:8]	0x07	RW	[7:0] CISCTL_hb[15:8]
0x0343	CISCTL_hb[7:0]	0x80	RW	[7:0] CISCTL_hb[7:0]
0x0346	CISCTL_row_start[11:8]	0x00	RW	[3:0] CISCTL_row_start[10:8]
0x0347	CISCTL_row_start[7:0]	0x02	RW	[7:0] CISCTL_row_start[7:0]
0x070c	CISCTL_col_start [7:0]	0x00	RW	[7:0] CISCTL_col_start [7:0]
0x070d	CISCTL_col_start [10:8]	0x00	RW	[2:0] CISCTL_col_start [7:0]
0x034a	CISCTL_win_height[11:8]	0x05	RW	[3:0] CISCTL_win_height[10:8]
0x034b	CISCTL_win_height[7:0]	0x18	RW	[7:0] CISCTL_win_height[7:0]
0x0348	CISCTL_win_width[11:8]	0x09	RW	[3:0] CISCTL_win_width[11:8]
0x0349	CISCTL_win_width[7:0]	0x0c	RW	[7:0] CISCTL_win_width[7:0]
0x0340	Framelength[13:8]	0x07	RW	[5:0] Framelength_high[13:8]
0x0341	Framelength[7:0]	0x0d	RW	[7:0] Framelength_low[7:0]
0x029d	min_vb[7:0]	0x10	RW	
0x0213	CISCTL_vs_st	0x18	RW	vs_st
0x0214	CISCTL_vs_et	0x04	RW	vs_et

CSI/PHY1.0

Address	Name	Default	R/W	Description
0x0100	Lane_Ena ULP_Ena Line_sync_mode MIPI_Ena	0x20	RW	[3] Lane_Ena [2] ULP_Ena [1] Line_sync_mode [0] MIPI_Ena
0x0180	DPHY_analog_mode1	0x06	RW	[6] mipi_en [5:4] disable_set [3:0] mipi_diff

0x0181	DPHY_analog_mode2	0x00	RW	[7] dphy_data3_en [6] dphy_data2_en [5] dphy_data1_en [4] dphy_data0_en [3] data3delay1s [2] data2delay1s [1] data1delay1s [0] data0delay1s
0x0182	DPHY_analog_mode3	0x00	RW	[7:6] data3lp_drv_10 [5:4] data2lp_drv_10 [3:2] data1lp_drv_10 [1:0] data0lp_drv_10
0x0183	DPHY_analog_mode4	0x05	RW	[7:6] data3ctr [5:4] data2ctr [3:2] data1ctr [1:0] data0ctr
0x0184	DPHY_analog_mode5	0x05	RW	[7:6] dat3hs_ph [5:4] dat2hs_ph [3:2] dat1hs_ph [1:0] dat0hs_ph
0x0185	DPHY_analog_mode6	0x00	RW	[7] data3lp_drv_2 [6] data2lp_drv_2 [5] data1lp_drv_2 [4] data0lp_drv_2 [0] dphy_clk_en
0x0186	DPHY_analog_mode7	0x53	RW	[7:6] clkctr [5:4] clkhs_ph [3:2] clklp_drv_10 [1] clklane_p2s_sel NA clkp2s_en [0] clkdelay1s
0x0111	LDI_set	0x2b	RW	[7:6] vc_id [5:4] data type raw10/8
0x010e	LWC_set[15:8]	0x0b	RW	[7:0] LWC_set_1
0x010d	LWC_set[7:0]	0x40	RW	[7:0] LWC_set_2
0x0112	MIPI_Raw_mode[15:8]	0x0a	RW	0a: Raw10 08:Raw8
0x0113	MIPI_Raw_mode[7:0]	0x0a	RW	0a: Raw10 08:Raw8
0x0114	MIPI_Lane_num[1:0]	0x03	RW	[1:0] 00: 1lane 01:2lane 10:4lane
0x0115	DPHY_mode	0x10	RW	[6] mipi para invar when div2 [5] DATA lane gate [4] all_lane_open_mode [3:2] switch_msb_mode [1:0] clklane_mode

0x0116	LP_set	0x29	RW	[7:6] hi-z [5:4] use define
0x0120	T_init_set	0x80	RW	[7:0] T_init_set
0x0121	T_LPX_set	0x10	RW	[7:0] T_LPX_set
0x0122	T_CLK_HS_PREPARE_set	0x05	RW	[7:0] T_CLK_HS_PREPARE_set
0x0123	T_CLK_zero_set	0x20	RW	[7:0] T_CLK_zero_set
0x0124	T_CLK_PRE_set	0x02	RW	[7:0] T_CLK_PRE_set
0x0125	T_CLK_POST_set	0x20	RW	[7:0] T_CLK_POST_set
0x0126	T_CLK_TRAIL_set	0x08	RW	[7:0] T_CLK_TRAIL_set
0x0127	T_HS_exit_set	0x10	RW	[7:0] T_HS_exit_set
0x0128	T_wakeup_set	0xa0	RW	[7:0] T_wakeup_set
0x0129	T_HS_PREPARE_set	0x06	RW	[7:0] T_HS_PREPARE_set
0x012a	T_HS_Zero_set	0x0a	RW	[7:0] T_HS_Zero_set
0x012b	T_HS_TRAIL_set	0x08	RW	[7:0] T_HS_TRAIL_set

OUT

Address	Name	Default	R/W	Description
0x008c	Test image	0x10	RW	[2] input test image
0x0098	out_win_y1[10:8]	0x00	RW	[3:0] out_win_y1
0x0099	out_win_y1[7:0]	0x00	RW	[7:0] out_win_y1
0x009a	out_win_x1[11:8]	0x00	RW	[3:0] out_win_x1
0x009b	Out_win_x1[7:0]	0x00	RW	[7:0] out_win_x1
0x0096	Out_win_height[11:8]	0x06	RW	[3:0] out_win_helght[11:8]
0x0097	Out_win_height[7:0]	0x82	RW	out_win_helght[7:0]
0x0094	Out_win_width[11:8]	0x0b	RW	[3:0] out_win_width[11:8]
0x0095	Out_win_width[7:0]	0x90	RW	out_win_width[7:0]
0x009c	Win_mode[0]	0x01	RW	Win_mode
0x008e	Out_win_offset	0x05	RW	[3:0] Out_win_offset for auto_updown[3:2] out_offset_y1=2 for auto_mirror[1:0] out_offset_x1=2

OB OFFSET

Address	Name	Default	R/W	Description
0x0038	WB_offset_Gr	0x40	RW	WB_offset_Gr
0x0039	WB_offset_R	0x40	RW	WB_offset_R
0x003a	WB_offset_B	0x40	RW	WB_offset_B
0x003b	WB_offset_Gb	0x40	RW	WB_offset_Gb

Gain

Address	Name	Default	R/W	Description
0x0064	Auto_pregain[9:6]	0x01	RW	[3:0] Auto_pregain[9:6]
0x0065	Auto_pregain[5:0]	0x00	RW	[7:2] Auto_pregain[5:0]
0x0914	Analog_PGA_gain[7:0]	0x00	RW	[7:0] analog_gain[7:0]
0x0915	Analog_PGA_gain[12:8]	0x00	RW	[4:0] analog_gain[12:8]
0x0225	Analog_PGA_gain[13]	0x00	RW	[0] analog_gain[13]
0x00b8	Col_gain[11:6]	0x00	RW	[5:0]col_gain[11:6]
0x00b9	Col_gain[5:0]	0x00	RW	[5:0]col_gain[5:0]